



SMD Auto X8G HT150C Flex, Ceramic, 0.027 uF, 10%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, Automotive Grade, 1812, 2.3 mm



General Information		
Series	SMD Auto X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable, Automotive Grade	
Features	High Temperature, Ultra-Stable, Automotive Grade	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
Qualifications	AEC-Q200	
AEC-Q200	Yes	
Typical Component Weight	67 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions	
Chip Size	1812
L	4.5mm +/-0.4mm
W	3.2mm +/-0.3mm
T	1mm +/-0.10mm
S	2.3mm MIN
В	0.7mm +/-0.35mm

Т	1mm +/-0.10mm
S	2.3mm MIN
В	0.7mm +/-0.35mm
Packaging Specifications	

В	0.7mm +/-0.35mm	Temperature Ran
		Temp. Coefficien
Packaging Specifications		Capacitance Cha
Packaging	T&R, 180mm, Plastic Tape	Reference to +25° Applied (TCC)
Packaging Quantity	1000	Dissipation Factor
		Aging Pate

Specifications	
Capacitance	0.027 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	250 VDC
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	37.037 GOhms

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